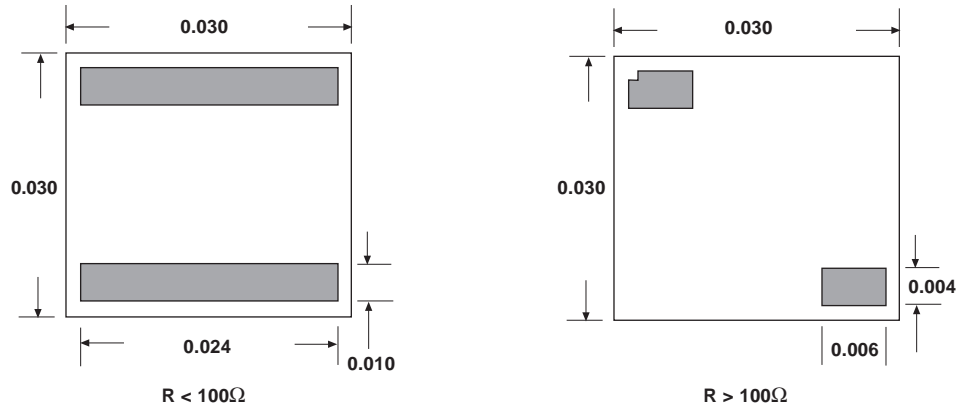


DIMENSIONS in inches

SCHEMATIC


MECHANICAL SPECIFICATIONS in inches	
PARAMETER	
Chip size	0.030 x 0.030 ± 0.003 (1.27 x 1.27 ± 0.076mm)
Chip thickness	0.010 ± 0.002 (0.25 ± 0.05mm)
Chip substrate material	99.6% alumina, 2-4 microinch finish
Resistor material	Nichrome
Bonding pad size	0.004 x 0.006 (0.100 x 0.15mm) minimum
Number of pads	2
Pad material	25kÅ minimum gold standard
Backing	None

OPTIONS: Terminations: Aluminum, Nickel solder
 Gold back for solder die attach
 Contact Applications Engineer

ORDERING INFORMATION						
Example: 100% visualled, 50Ω, ± 10%, ± 50ppm/°C TCR, Gold Terminations, Resistor coated (thermal set plastic)						
W	CC2	5000	B	K	D	GC
INSPECTION /PACKAGING	PRODUCT FAMILY	RESISTOR VALUE	MULTIPLIER CODE	TOLERANCE CODE	TCR	TERMINATIONS
W = 100% visually inspected parts in matrix tray per MIL-STD-883		Use first 4 significant digits of resistor	B = 0.01 A = 0.1 0 = 1 1 = 10 2 = 100	A = 0.05%* B = 0.1%* C = 0.25%* D = 0.5% F = 1.0% G = 2.0% J = 5.0% K = 10% *Coating standard	A = ± 10ppm/°C B = ± 25ppm/°C D = ± 50ppm/°C E = ± 100ppm/°C	G = Gold GC = Gold Coated
X = Sample, commercial visually inspected parts loaded in matrix trays (4% AQL)						

This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.